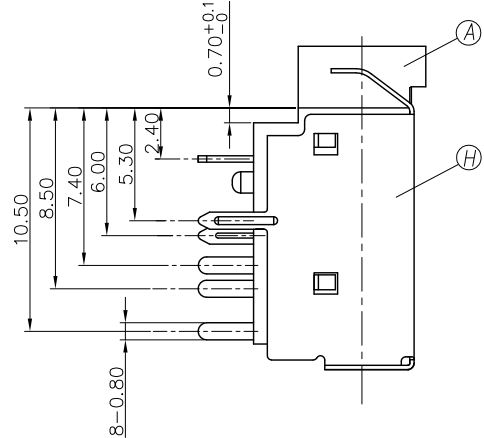
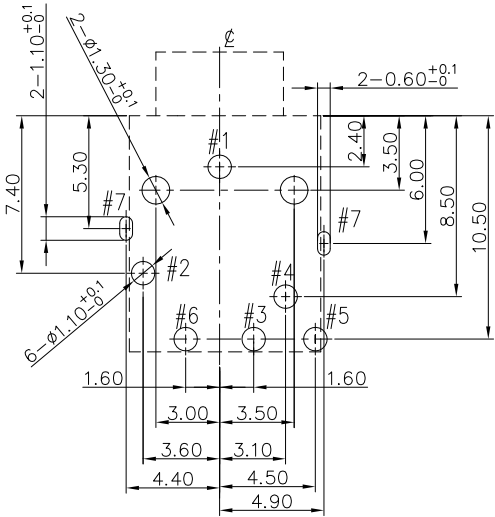
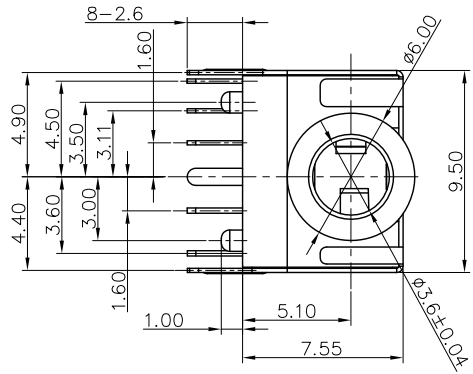
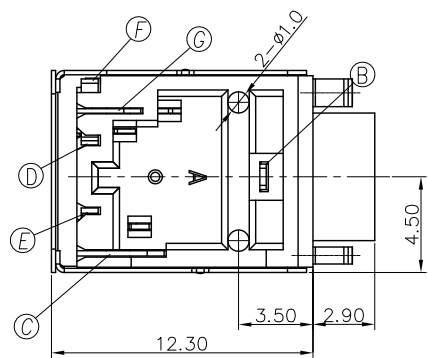
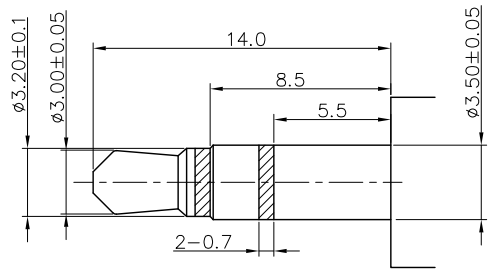


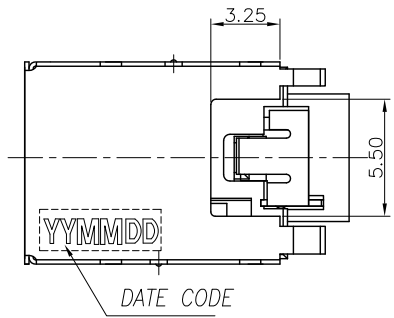
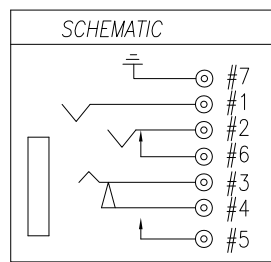
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO:T131028-2A	MARS	2013.12.24



RECOMMENDED P.C.B. LAYOUT
TOP VIEW (TOL.±0.05)



RECOMMENDED PLUG
3-POLE



SPECIFICATIONS:

- ELECTRICAL CHARACTERISTICS:
 - RATING: 12V 1A
 - CONTACT RESISTANCE: 30mΩ MAX.(INITIAL)
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE
 - INSULATION RESISTANCE: 100MΩ MIN. MEASURED BY 500 VDC
- MECHANICAL CHARACTERISTICS:
 - INSERTION FORCE :0.3~3KGF
 - WITHDRAWAL FORCE : 0.3~3.0KGF
- LIFE TEST: 5,000 CYCLES MIN.
- OTHER GENERAL SPEC. TO REFER "2.5 3.5 PHONE JACK-SPEC".
- TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
- HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
- FOR REFLOW SOLDERING LEAD-FREE PROCESS.
- PACKAGING:TAPE&REEL



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
H	SHIELDING	1	COPPER ALLOY,0.2T	Ni 60u"
G	TRANSFER TERMINAL	1	COPPER ALLOY,0.2T	GOLD FLASH ON CONTACT AREA Sn 120u" ON SOLDER TAIL ALL OVER 50u" Ni
F	BREAK TERMINAL	1	COPPER ALLOY,0.2T	GOLD FLASH ON CONTACT AREA 50u" Ni Min.
E	SHUNT TERMINAL-A	1	BRASS 0.25T	GOLD FLASH ON CONTACT AREA 50u" Ni Min.
D	RING SPRING	1	COPPER ALLOY,0.2T	Au 30u" ON CONTACT AREA Sn 120u" ON SOLDER TAIL ALL OVER 50u" Ni
C	TIP SPRING	1	COPPER ALLOY,0.25T	Au 30u" ON CONTACT AREA GOLD FLASH ON SOLDER TAIL ALL OVER 50u" Ni
B	EARTH	1	COPPER ALLOY,0.3T	Au 30u" ON CONTACT AREA GOLD FLASH ON SOLDER TAIL ALL OVER 50u" Ni
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLUE(PAN# 284C)
UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司		
DECIMALS: X:±0.5 X.X:±0.3 X.XX:±0.2		ANGLES: X:±2° X.X:±1°		TITLE: 3.5Ø PHONE JACK
		DWN	MARS	PART NO. 2SJ-K351-003F
		CHKD	BRUCE	SCALE:4:1 UNIT: MM
		APVD	Lussen	SIZE: A3 SHEET:1 OF 1 REV:A
CUSTOMER COPY				